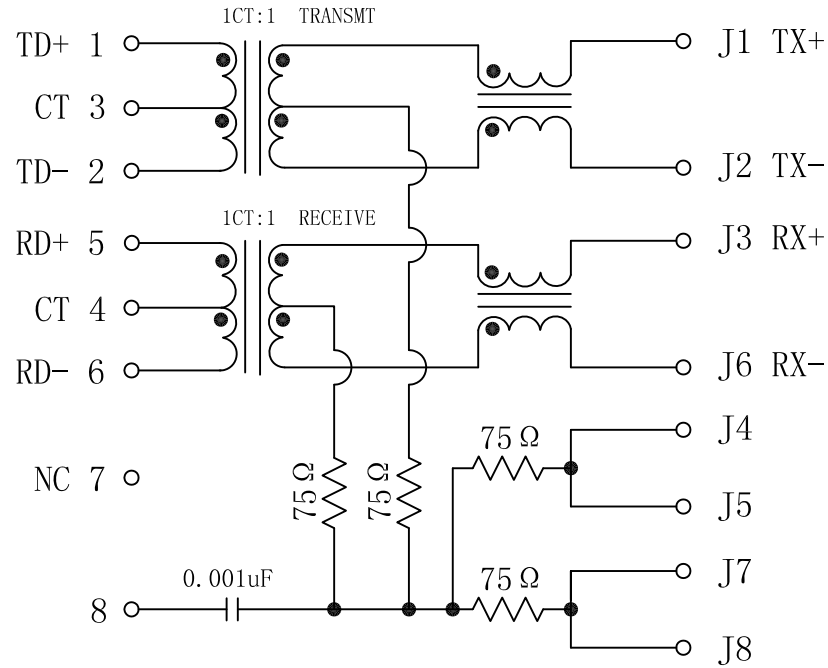


# Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2014/10/28	

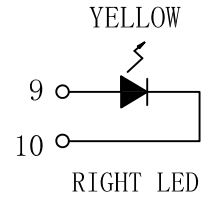
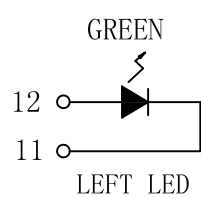
PCB SIDE TO PHY



CABLE

## Electrical Specifications @25°C

- Turns Ratio ( $\pm 2\%$ ) :  
TX=1CT:1CT      RX=1CT:1CT
- OCL: 350uH Min  
@100KHz, 100mV, 8mA bias current
- Insertion Loss:  
1-65MHz:-1.0dB Max
- Return Loss(dB Min @100  $\Omega$   $\pm 15 \Omega$ ) :  
1-10MHz:-20      30MHz:-16  
60-80MHz:-12
- Crosstalk(dB Min) :  
1-10MHz:-40      30-60MHz:-35  
60-100MHz:-30
- Common Mode Rejection(dB Min) :  
1-50MHz:-30      50-130MHz:-20
- Isolation Voltage: 1500Vrms Min
- Operating Temperature: -40°C ~ +85°C.



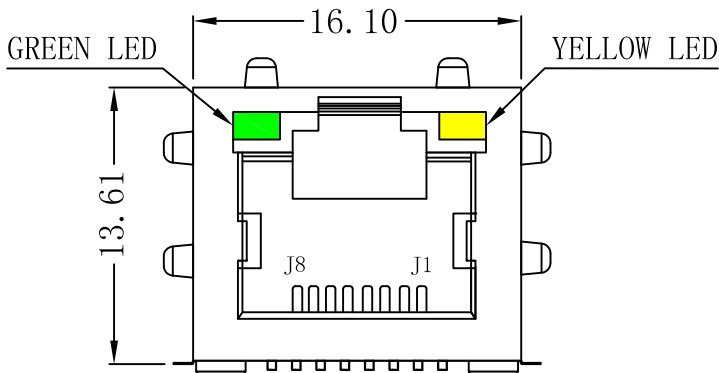
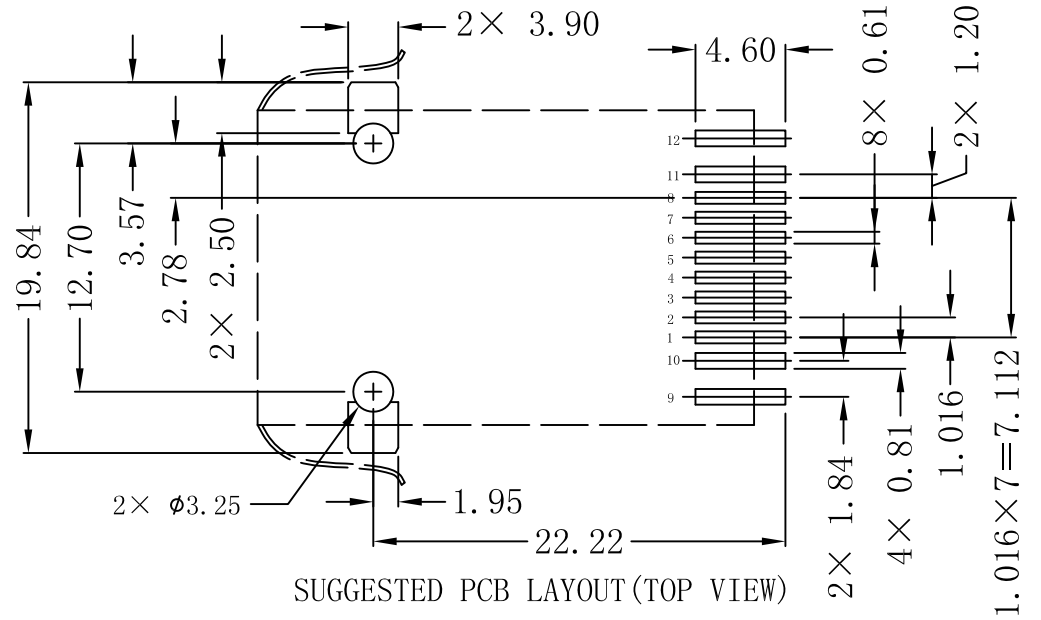
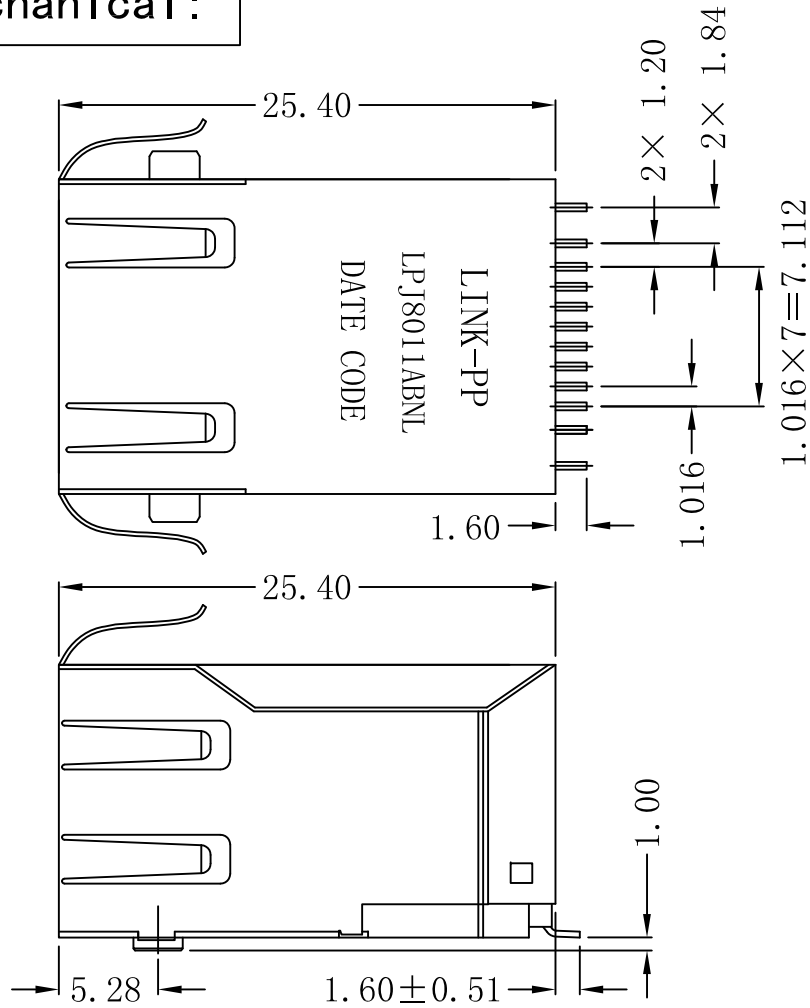
Emitting Color	$\lambda_p$ (nm)	VF@IF=20mA	IR @VR=5V
Green	570	1.8~2.6V	10 $\mu$ A max
Yellow	585	1.8~2.6V	10 $\mu$ A max



X:X	$\pm 0.30$	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	$\pm 0.25$	CHKD:	
X:XXX	$\pm 0.05$	DR: TOM	
ANGLES	$\pm 1^\circ$	UNIT: mm	TITLE: Surface Mount 1x1 Tab-Up Jack With 10/100 Magnetic SMT
			PART NO.: LPJ8011ABNL
	SCALE: 2/1	SHEET: 1/2	REV: A
			DWG NO.: LP14102801

# Mechanical :

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2014/10/28	



### NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:  
Housing: Thermoplastic UL94V-0  
Contact/Shield: Copper alloy  
Shield plating: Nickel  
Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max  
Wave solder tip temperature time: 5 Sec Max

X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.25	CHKD:	TITLE: Surface Mount 1x1 Tab-Up Jack With 10/100 Magnetic SMT	
X:XXX	±0.05	DR: TOM	PART NO.: LPJ8011ABNL	
ANGLES	±1°	UNIT: mm	REV: A	DWG NO.: LP14102801
SCALE: 2/1		SHEET: 2/2		